

MECHANICAL CASE OUTLINE

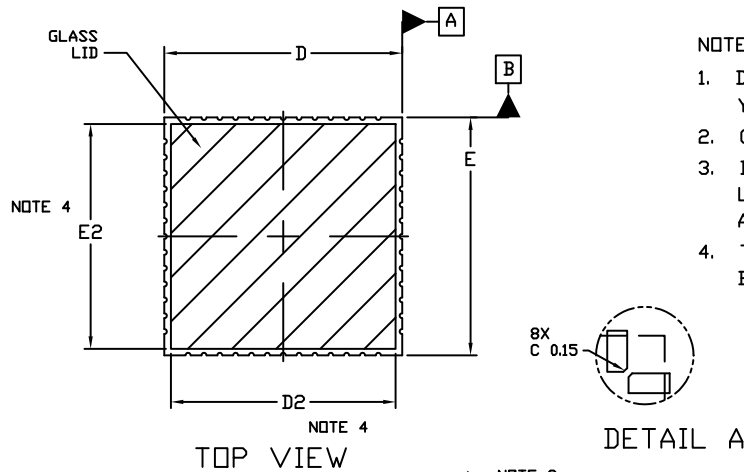
PACKAGE DIMENSIONS

ON Semiconductor®



LCC52, 19.05x19.05 CASE 115AP-01 ISSUE O

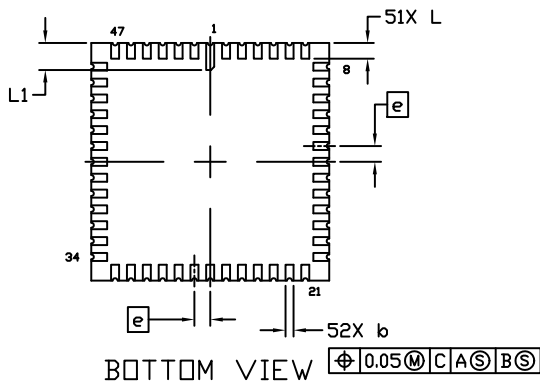
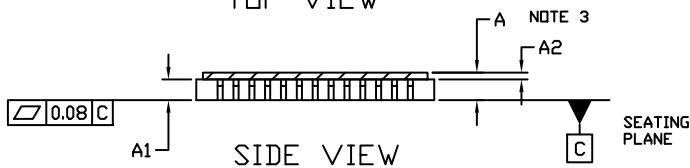
DATE 30 JUN 2011



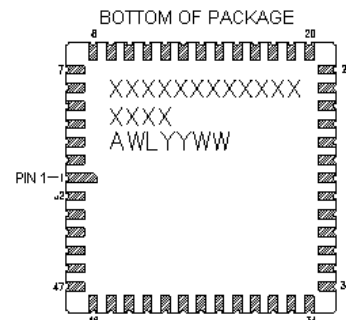
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY AND LID BUT DOES NOT INCLUDE HEATSINKS OR OTHER ATTACHED FEATURES.
4. THE LID DEFINED BY DIMENSIONS D2 AND E2 MUST BE LOCATED WITHIN DIMENSIONS D AND E.

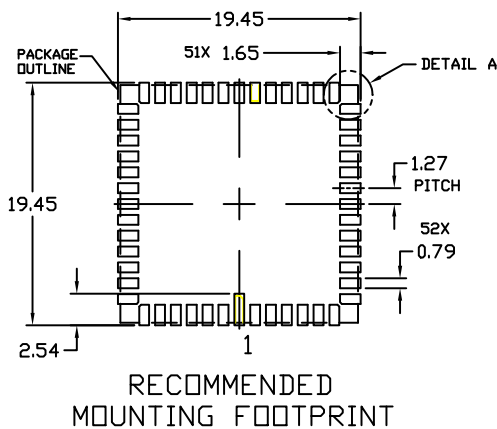
DIM	MILLIMETERS	
	MIN.	MAX.
A	1.85	2.55
A1	1.65 REF	
A2	0.55 REF	
b	0.56	0.72
D	18.80	19.43
D2	18.00 REF	
E	18.80	19.43
E2	18.00 REF	
e	1.27 BSC	
L	1.14	1.40
L1	1.96	2.36



GENERIC MARKING DIAGRAM



- XXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- NNNN = Serial Number



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